

L Number	Hits	Search Text	DB	Time stamp
1	2521	measure\$ same first same workpiece	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/11/19 14:38
2	1685	(measure\$ same first same workpiece) and method	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/11/19 14:39
3	1539	((measure\$ same first same workpiece) and method) and second	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/11/19 14:41
4	231	((measure\$ same first same workpiece) and method) and second) and semiconductor	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/11/19 16:14
5	1381	measuring same thickness same layer same first	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/11/19 16:15
6	779	measuring same thickness same layer same first same second	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/11/19 16:15
7	207	(measuring same thickness same layer same first same second) and operating	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/11/19 16:19
8	4	((measuring same thickness same layer same first same second) and operating) and recipe	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/11/19 16:15
9	5	("5590051" "5637351" "5724144" "6060370" "6306669").PN.	USPAT	2003/11/19 16:17
10	64	((measuring same thickness same layer same first same second) and operating) and semiconductor	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/11/19 16:20
11	181	((measuring same thickness same layer same first same second) and operating) and method	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/11/19 16:20